



### **L7: Memory Basics and Timing**



#### Acknowledgements:

Materials in this lecture are courtesy of the following people and used with permission.

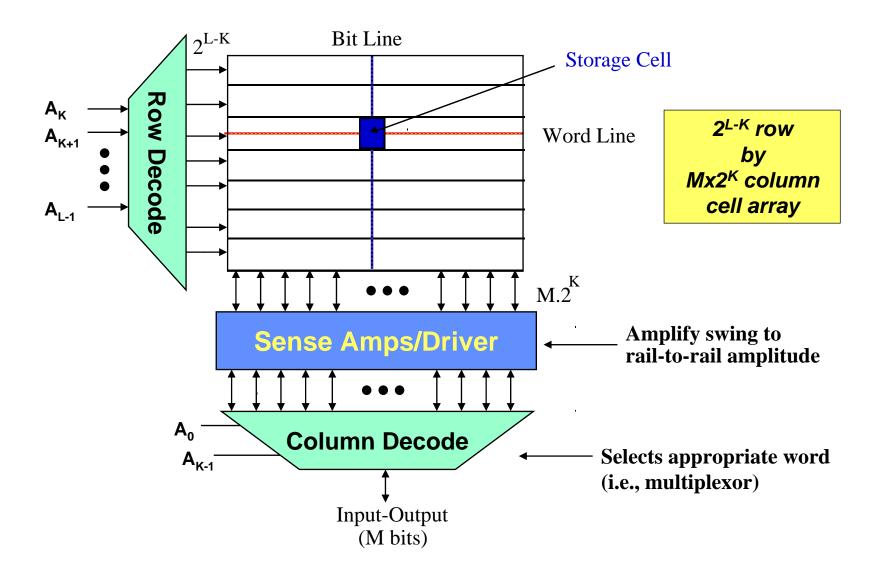
- Rex Min
- Rabaey, J., A. Chandrakasan, B. Nikolic. *Digital Integrated Circuits: A Design Perspective*. Prentice Hall, 2003, chapter 10.

<b>Read-Write Memory</b>		Non-Volatile Read-Write Memory	Read-Only Memory (ROM)	
Random Access	Non-Random Access	EPROM E <sup>2</sup> PROM	Mask-Programmed	
SRAM DRAM	FIFO LIFO	FLASH		

### **Key Design Metrics:**

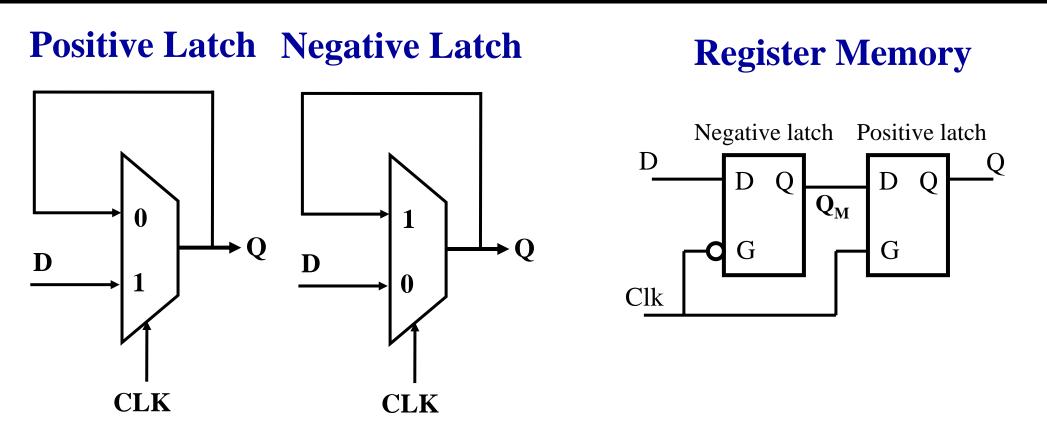
- **1. Memory Density (number of bits/μm<sup>2</sup>) and Size**
- 2. Access Time (time to read or write) and Throughput
- 3. Power Dissipation





### Latch and Register Based Memory

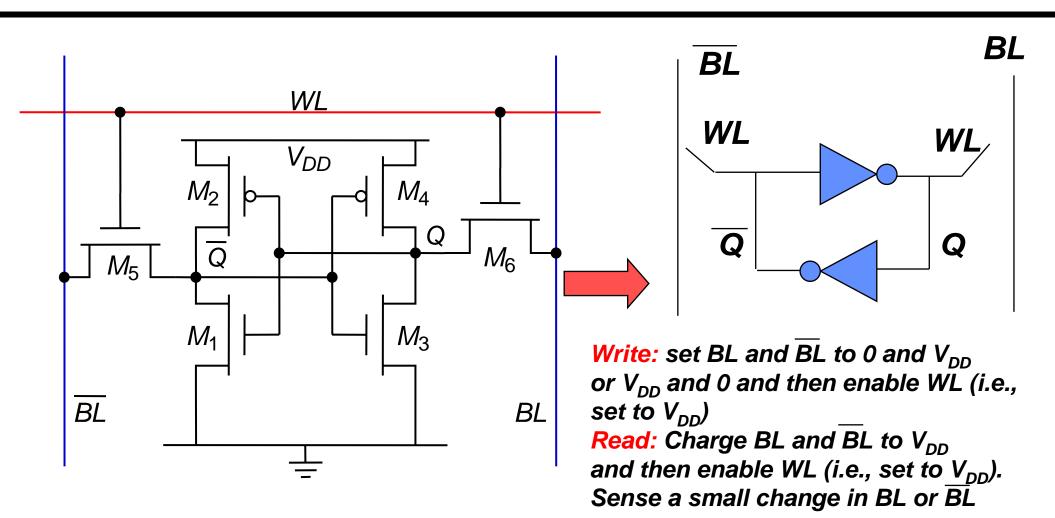




 Works fine for small memory blocks (e.g., small register files)
 Inefficient in area for large memories – density is the key metric in large memory circuits

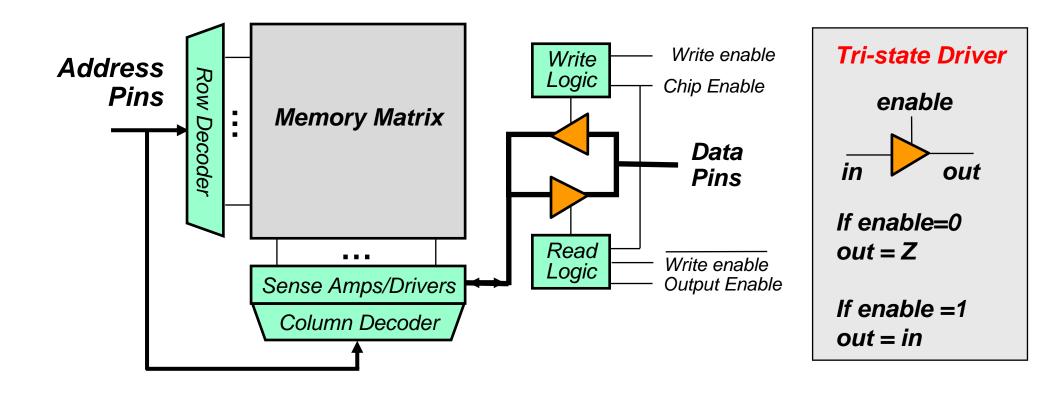
### How do we minimize cell size?

### **Static RAM (SRAM) Cell (The 6-T Cell)**



- State held by cross-coupled inverters (M1-M4)
- Static Memory retains state as long as power supply turned on
- Feedback must be overdriven to write into the memory

### Interacting with a Memory Device



- Address pins drive row and column decoders
- Data pins are bidirectional and shared by reads and writes
- Output Enable gates the chip's tristate driver
- Write Enable sets the memory's read/write mode
- Chip Enable/Chip Select acts as a "master switch"

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### MCM6264C 8k x 8 Static RAM



#### Same (bidirectional) data bus On the outside: used for reading and writing Chip Enables (E1 and E2) Address -E1 must be low and E2 must be high to enable the chip Chip Enables E1 **MCM6264C** Write Enable (W) Data DQ[7:0] When low (and chip is enabled), Write Enable W the values on the data bus are written to the location selected by Output Enable $\overline{G}$ . the address bus **Output Enable (G)** When low (and chip is enabled On the inside: П with W=0), the data bus is driven with the value of the selected A2 memory location DQ[7:0] A3 Decode E1 28 Vcc NC [ 1 • A4 Memory matrix E2 . A12 2 W 27 Π A5 256 rows Α7 3 E2 26 A7 Row 32 Column A6 A8 25 A8 A5 Π 5 24 A9 Δ9 W 23 🛛 A4 🛛 A11 A11 **Pinout** 22 🛛 G A3 🛛 7 G . . . 21 A10 A2 🛛 8 Sense Amps/Drivers A1 20 🛛 E1 Π 9 Column Decoder DQ7 A0 0 10 19 П DQ0 0.11 18 🛛 DQ6

A0 A1 A10 A12

DQ1

DQ2 13

V<sub>SS</sub> [] 14

12

DQ5

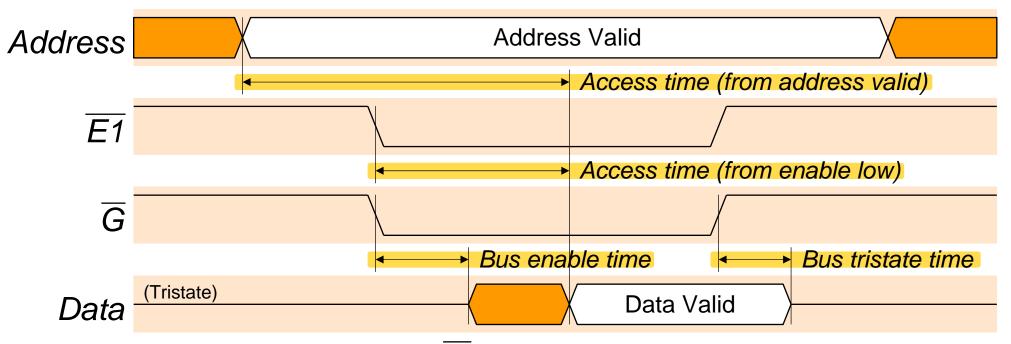
DQ4

17

16 15 DQ3

### **Reading an Asynchronous SRAM**



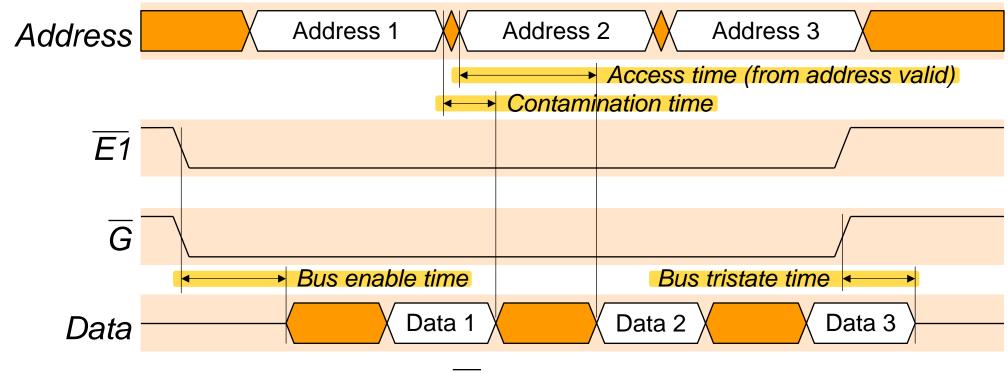


E2 assumed high (enabled), W = 1 (read mode)

- Read cycle begins when all enable signals (E1, E2, G) are active
- Data is valid after read access time
  □ Access time is indicated by full part number: MCM6264CP-12 → 12ns
- Data bus is tristated shortly after G or E1 goes high







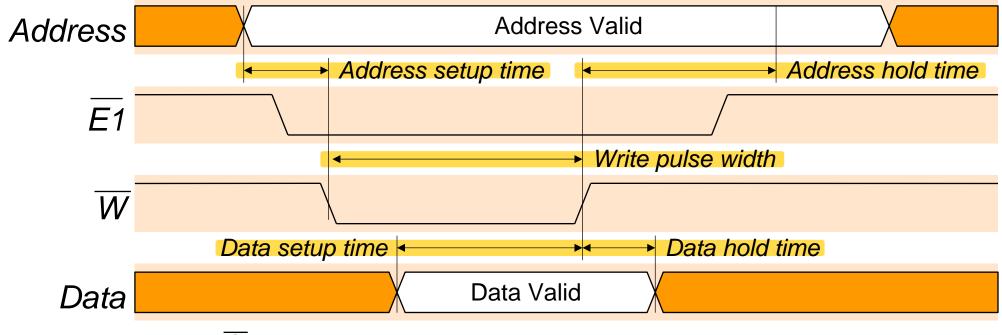
E2 assumed high (enabled),  $\overline{W} = 1$  (read mode)

Can perform multiple reads without disabling chip

Data bus follows address bus, after some delay

### Writing to Asynchronous SRAM





E2 and  $\overline{G}$  are held high

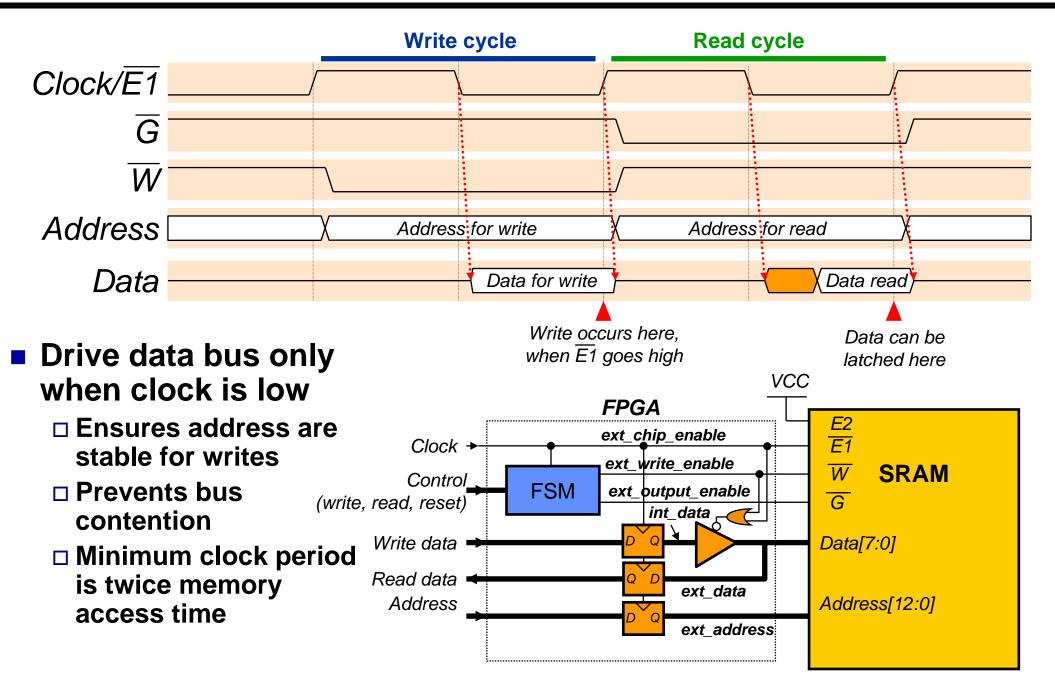
Data latched when W or E1 goes high (or E2 goes low)

- □ Data must be stable at this time
- □ Address must be stable before W goes low

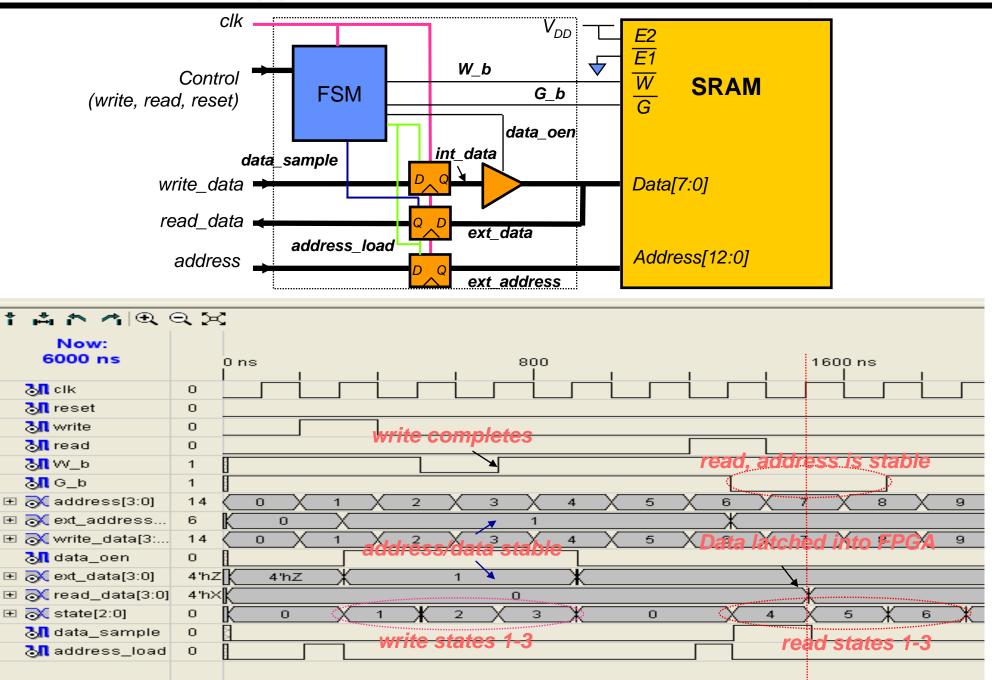
# Write waveforms are more important than read waveforms Glitches to address can cause writes to random addresses!

### **Sample Memory Interface Logic**





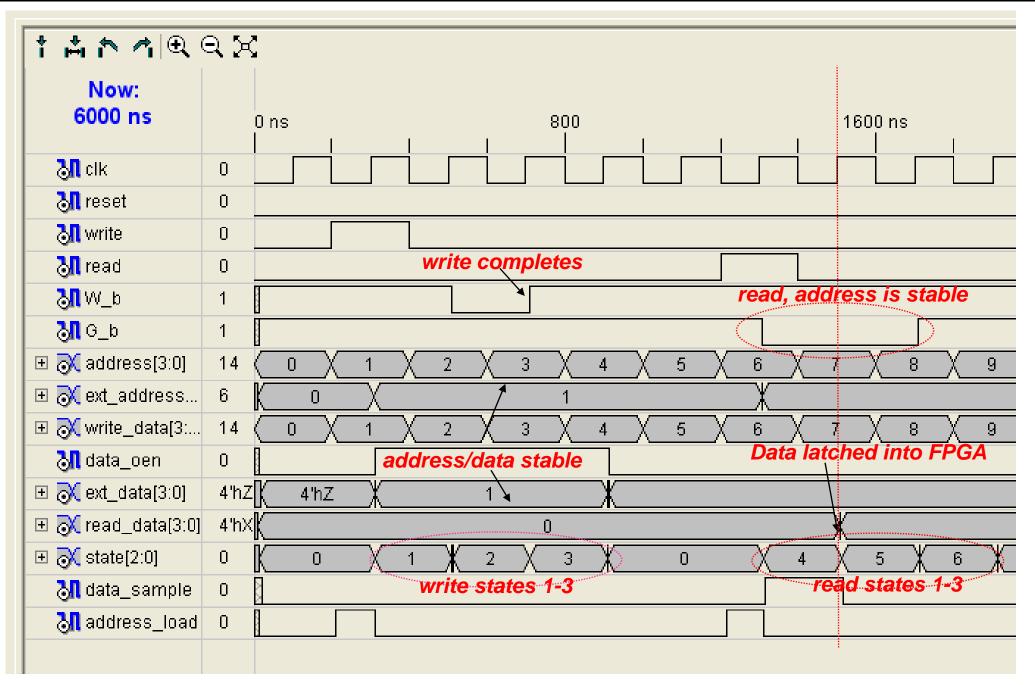
### Multi-Cycle Read/Write (less aggressive, recommended timing)



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### **Simulation from Previous Slide**



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### Verilog for Simple Multi-Cycle Access

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module memtest (clk, reset, G\_b, W\_b, address, ext\_address, write\_data, read\_data, ext\_data, read, write, state, data oen, address load, data sample); input clk, reset, read, write; output G b, W b; output [12:0] ext address; reg [12:0] ext address; input [12:0] address; input [7:0] write\_data; output [7:0] read\_data; reg [7:0] read\_data; inout [7:0] ext data; reg [7:0] int data; output [2:0] state; reg [2:0] state, next; output data\_oen, address\_load, data\_sample; reg G\_b, W\_b, G\_b\_int, W\_b\_int, address\_load, data oen, data oen int, data sample; wire [7:0] ext\_data; parameter IDLE = 0; parameter write1 = 1; parameter write2 = 2; parameter write3 = 3; parameter read1 = 4; parameter read2 = 5; parameter read3 = 6; 1/4

assign ext\_data = data\_oen ? int\_data : 8'hz;

// Sequential always block for state assignment

always @ (posedge clk) begin if (!reset) state <= IDLE; else state <= next;

G\_b <= G\_b\_int; W\_b <= W\_b\_int; data\_oen <= data\_oen\_int; if (address\_load) ext\_address <= address; if (data\_sample) read\_data <= ext\_data; if (address\_load) int\_data <= write\_data; end

// note that address\_load and data\_sample are not
// registered signals

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### Verilog for Simple Multi-Cycle Access



// Combinational always block for next-state // computation always @ (state or read or write) begin W b int = 1; G b int = 1; Setup the address load = 0; **Default values** data\_oen\_int = 0; data\_sample = 0; case (state) IDLE: if (write) begin next = write1; address load = 1; data\_oen\_int = 1; end else if (read) begin next = read1;address load = 1; G b int = 0; end else next = IDLE; write1: begin next = write2; W b int = 0; data oen int =1; end

```
write2: begin
         next = write3;
         data oen int =1;
         end
  write3: begin
         next = IDLE;
         data oen int = 0;
         end
  read1: begin
         next = read2;
         G_b_int = 0;
         data_sample = 1;
         end
  read2: begin
         next = read3;
         end
  read3: begin
         next = IDLE;
         end
   default: next = IDLE;
  endcase
 end
endmodule
                                                   4/4
```

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#### Common device problems

- □ Bad locations: rare for individual locations to be bad
- □ Slow (out-of-spec) timing(s): access incorrect data or violates setup/hold
- □ Catastrophic device failure: e.g., ESD
- □ Missing wire-bonds/devices (!): possible with automated assembly
- □ Transient Failures: Alpha particles, power supply glitch

#### Common board problems

- □ Stuck-at-Faults: a pin shorted to V<sub>DD</sub> or GND
- Open Circuit Fault: connections unintentionally left out
- Open or shorted address wires: causes data to be written to incorrect locations
- Open or shorted control wires: generally renders memory completely inoperable

#### Approach

- Device problems generally affect the entire chip, almost any test will detect them
- Writing (and reading back) many different data patterns can detect data bus problems
- Writing unique data to every location and then reading it back can detect address bus problems



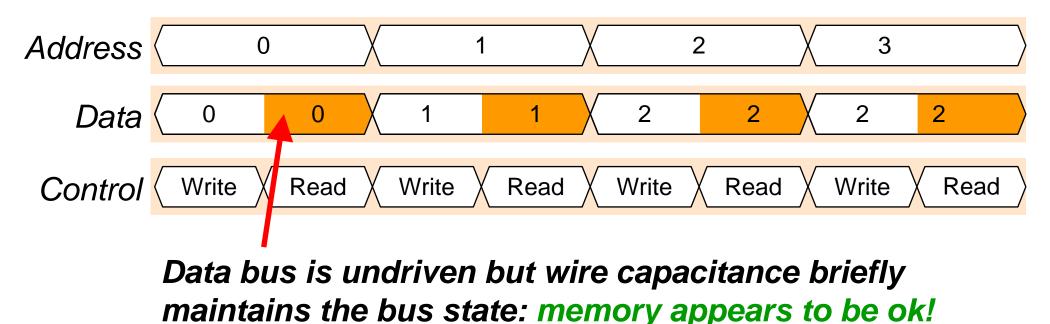


#### An idea that almost works

- 1. Write 0 to location 0
- 2. Read location 0, compare value read with 0
- 3. Write 1 to location 1
- 4. Read location 1, compare value read with 1
- 5. ...

#### What is the problem?

Suppose the memory was missing (or output enable was disconnected)



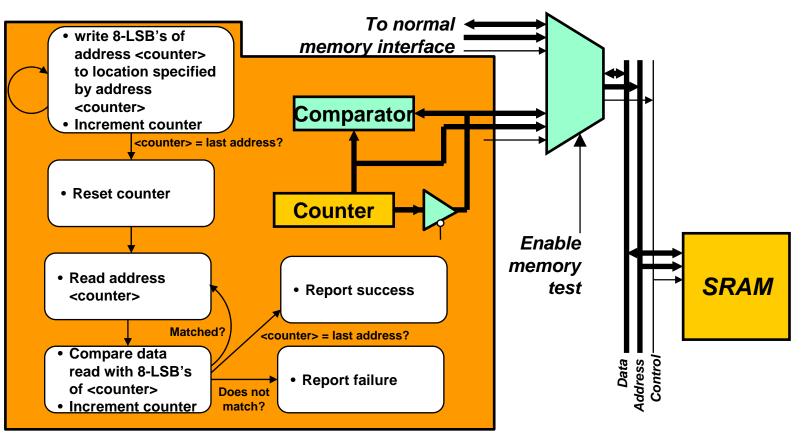


### **A Simple Memory Tester**



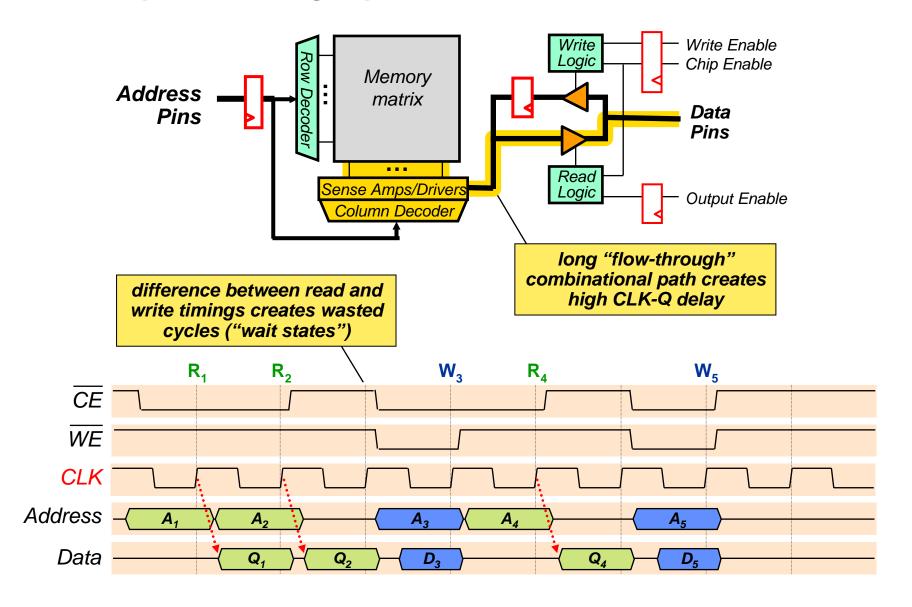
- Write to all locations, then read back all locations
  - Separates read/write to the same location with reads/writes of different data to different locations
  - both data and address busses are changed between read and write to same location)

- Write 0 to address 0
- Write 1 to address 1
- ...
- Write (*n* mod 256) to address n
- Read address 0, compare with 0
- Read address 1, compare with 1
- ..
- Read address n, compare with (*n* mod 256)



### **Synchronous SRAM Memories**

Clocking provides input synchronization and encourages more reliable operation at high speeds

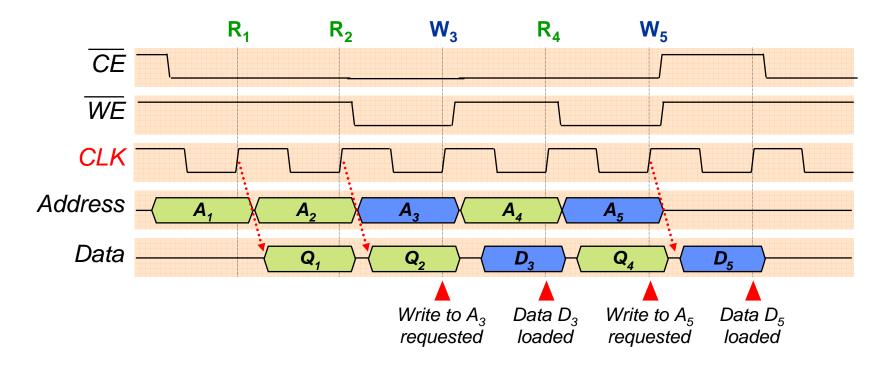


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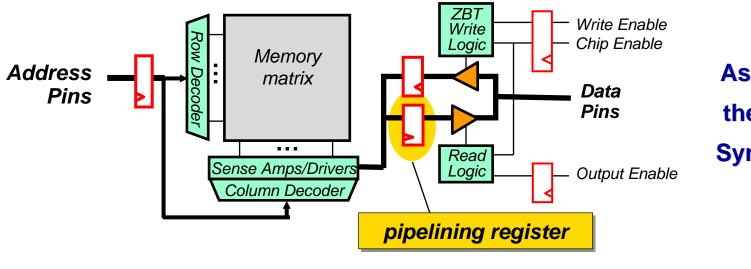
- The wait state occurs because:
  - □ On a read, data is available *after* the clock edge
  - □ On a write, data is set up before the clock edge
- **ZBT (**"zero bus turnaround") memories change the rules for writes
  - On a write, data is set up after the clock edge (so that it is read on the following edge)
  - □ Result: no wait states, higher memory throughput



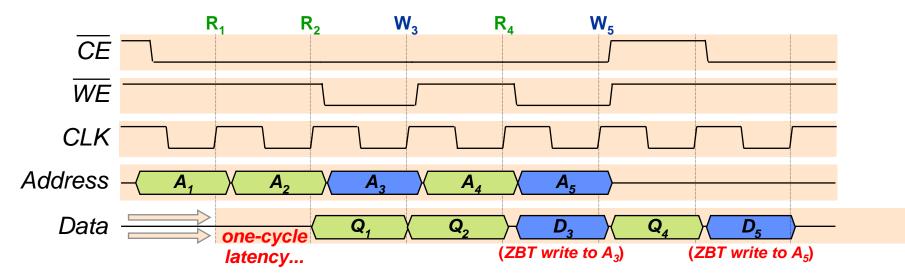
### **Pipelining Allows Faster CLK**



- Pipeline the memory by registering its output
  - □ Good: Greatly reduces CLK-Q delay, allows higher clock (more throughput)
  - □ Bad: Introduces an extra cycle before data is available (more latency)



As an example, see the CY7C147X ZBT Synchronous SRAM



### **IIII EPROM Cell – The Floating Gate Transistor IIII**

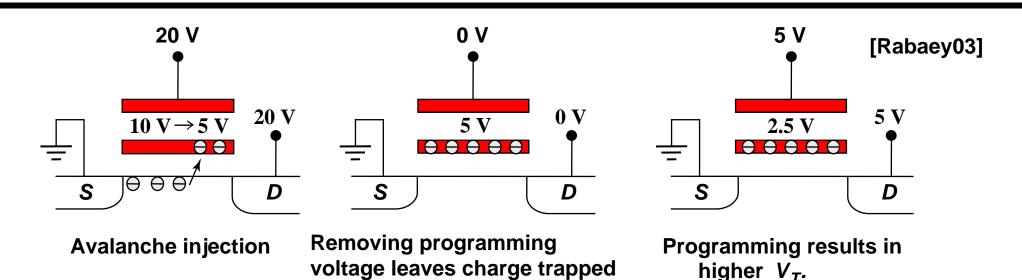


Image of EPROM Cell removed due to copyright restrictions.

Courtesy Intel

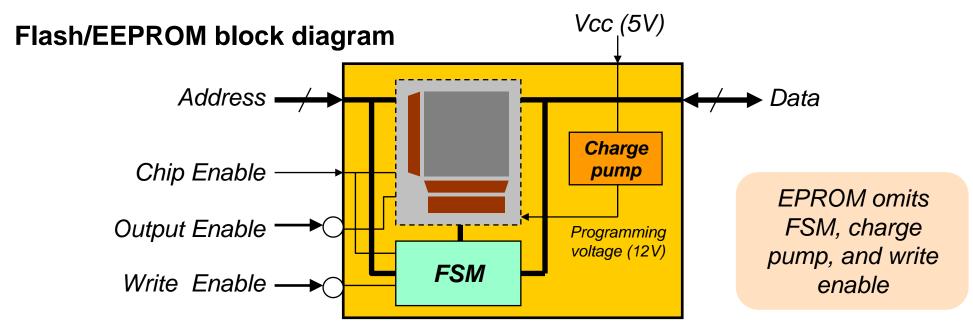
**EPROM Cell** 

#### This is a non-volatile memory (retains state when supply turned off)

## Interacting with Flash and (E)EPROM

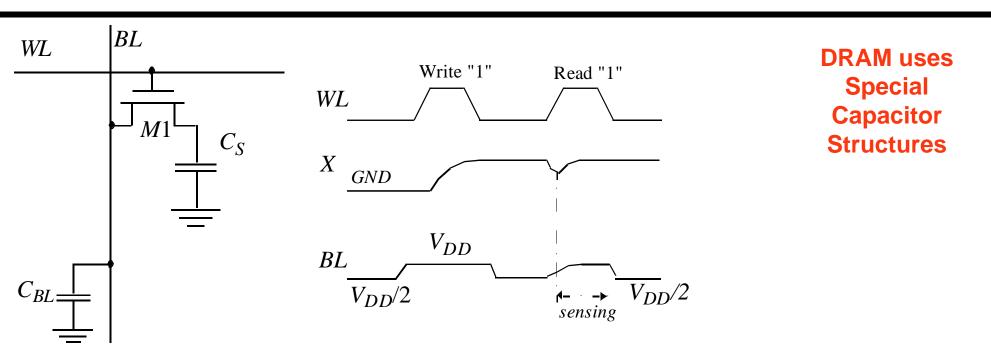


- Reading from flash or (E)EPROM is the same as reading from SRAM
- Vpp: input for programming voltage (12V)
  - □ EPROM: Vpp is supplied by programming machine
  - □ Modern flash/EEPROM devices generate 12V using an on-chip charge pump
- EPROM lacks a write enable
  - □ Not in-system programmable (must use a special programming machine)
- For flash and EEPROM, write sequence is controlled by an internal FSM
  - □ Writes to device are used to send signals to the FSM
  - Although the same signals are used, one can't write to flash/EEPROM in the same manner as SRAM



### **Dynamic RAM (DRAM) Cell**

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To Write: set Bit Line (BL) to 0 or  $V_{DD}$ & enable Word Line (WL) (i.e., set to  $V_{DD}$ )

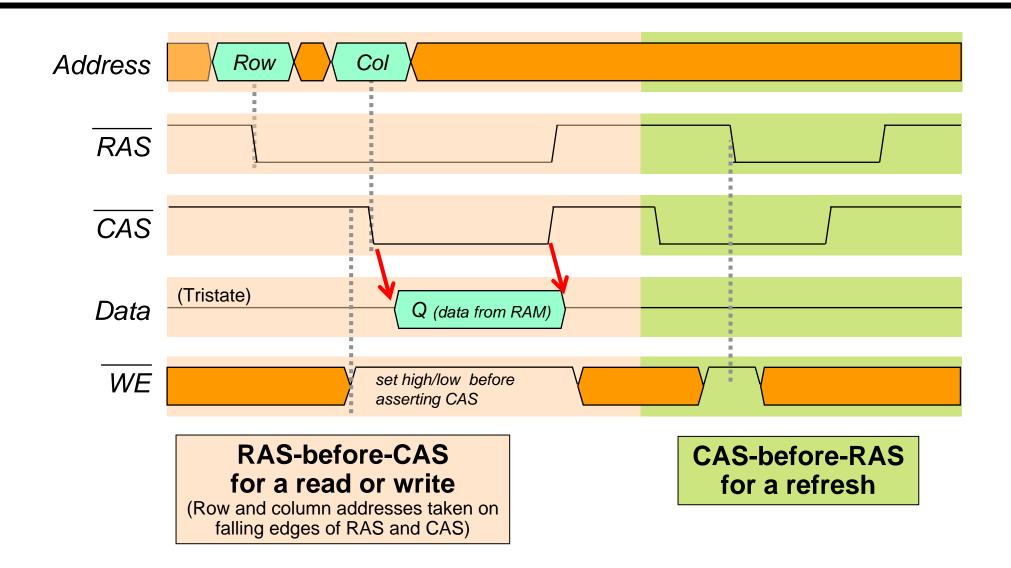
To Read: set Bit Line (BL) to  $V_{DD}$  /2 & enable Word Line (i.e., set it to  $V_{DD}$ )

- DRAM relies on charge stored in a capacitor to hold state
- Found in all high density memories (one bit/transistor)
- Must be "refreshed" or state will be lost high overhead

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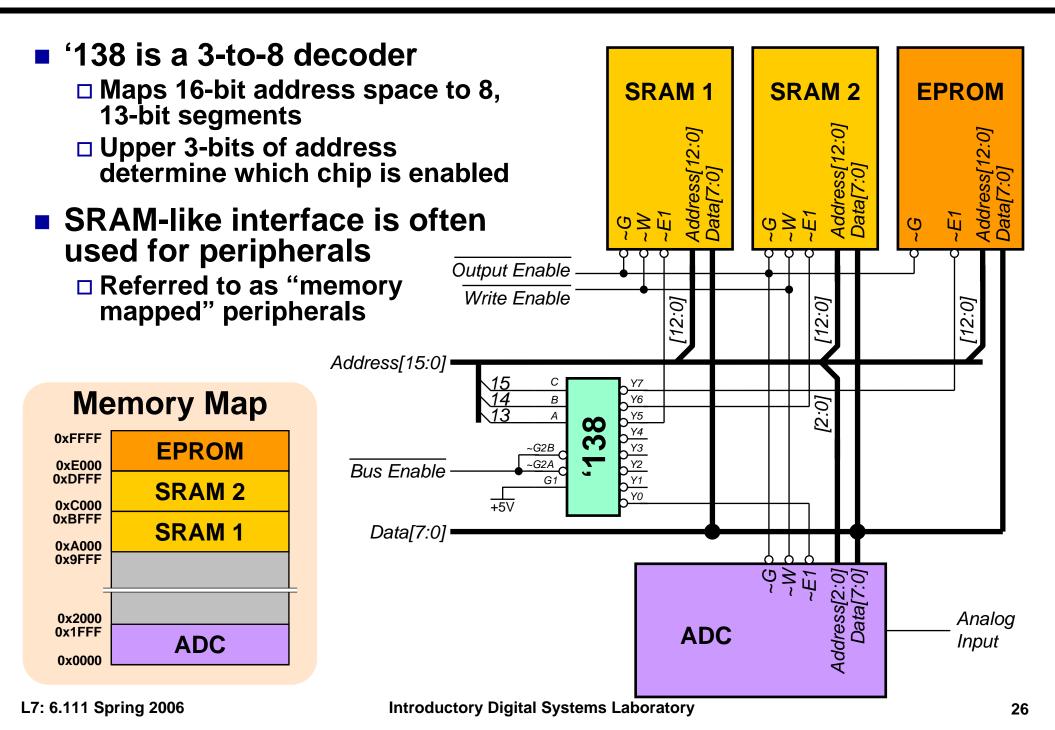


 Clever manipulation of RAS and CAS after reads/writes provide more efficient modes: early-write, read-write, hidden-refresh, etc. (See datasheets for details)

### **Addressing with Memory Maps**

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#### SRAM vs. DRAM

- SRAM holds state as long as power supply is turned on. DRAM must be "refreshed" – results in more complicated control
- DRAM has much higher density, but requires special capacitor technology.
- FPGA usually implemented in a standard digital process technology and uses SRAM technology

#### Non-Volatile Memory

- Fast Read, but very slow write (EPROM must be removed from the system for programming!)
- Holds state even if the power supply is turned off

#### Memory Internals

Has quite a bit of analog circuits internally -- pay particular attention to noise and PCB board integration

#### Device details

□ Don't worry about them, wait until 6.012 or 6.374





- control signals such as Write Enable should be registered
- a multi-cycle read/write is safer from a timing perspective than the single cycle read/write approach
- it is a bad idea to enable two tri-states driving the bus at the same time
- an SRAM does not need to be "refreshed" while a DRAM does
- an EPROM/EEPROM/FLASH cell can hold its state even if the power supply is turned off
- a synchronous memory can result in higher throughput